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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	46080000
Number of I/O	552
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma5h3f35c2n

Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering ^{(1), (2), (3)} (Part 2 of 2)

Transceiver Speed Grade	Core Speed Grade							
	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L	I3YY	I4
3 GX channel—8.5 Gbps	—	Yes	Yes	Yes	—	Yes	Yes ⁽⁴⁾	Yes

Notes to Table 1:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
 (2) Lower number refers to faster speed grade.
 (3) C2L, I2L, and I3L speed grades are for low-power devices.
 (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering ^{(1), (2)}

Transceiver Speed Grade	Core Speed Grade			
	C1	C2	I2	I3
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	—	—
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes

Notes to Table 2:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
 (2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	−0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	−0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	−0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	−0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	−0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	−0.5	3.9	V
V _{CCIO}	I/O power supply	−0.5	3.9	V

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Symbol	Description	Minimum	Maximum	Unit
V _{CCD_FPLL}	PLL digital power supply	−0.5	1.8	V
V _{CCA_FPLL}	PLL analog power supply	−0.5	3.4	V
V _I	DC input voltage	−0.5	3.8	V
T _J	Operating junction temperature	−55	125	°C
T _{STG}	Storage temperature (No bias)	−65	150	°C
I _{OUT}	DC output current per pin	−25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left side)	GX, GS, GT	−0.5	3.75	V
V _{CCA_GXBR}	Transceiver channel PLL power supply (right side)	GX, GS	−0.5	3.75	V
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	−0.5	3.75	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side)	GX, GS, GT	−0.5	1.35	V
V _{CCHIP_R}	Transceiver hard IP power supply (right side)	GX, GS, GT	−0.5	1.35	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side)	GX, GS, GT	−0.5	1.35	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side)	GX, GS, GT	−0.5	1.35	V
V _{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	−0.5	1.35	V
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	−0.5	1.35	V
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	−0.5	1.35	V
V _{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	−0.5	1.35	V
V _{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	−0.5	1.35	V
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	−0.5	1.35	V
V _{CCL_GTBR}	Transmitter clock network power supply (right side)	GT	−0.5	1.35	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	−0.5	1.8	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	−0.5	1.8	V

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to −2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Typ	Max ⁽⁴⁾	Unit
t _{RAMP}	Power supply ramp time	Standard POR	200 μs	—	100 ms	—
		Fast POR	200 μs	—	4 ms	—

Notes to Table 6:

- (1) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V_{CCBAT}. Stratix V devices will not exit POR if V_{CCBAT} stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
V _{CCA_GXBL} (1), (3)	Transceiver channel PLL power supply (left side)	GX, GS, GT	2.85	3.0	3.15	V
			2.375	2.5	2.625	
V _{CCA_GXBR} (1), (3)	Transceiver channel PLL power supply (right side)	GX, GS	2.85	3.0	3.15	V
			2.375	2.5	2.625	
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V _{CCHIP_R}	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V _{CCR_GXBL} (2)	Receiver analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) ⁽¹⁾

Symbol	Description	V _{CCIO} (V)	Typical	Unit
dR/dT	OCT variation with temperature without recalibration	3.0	0.189	%/ ^o C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.2	0.317	

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to 85°C.

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I _{IOPIN} (DC)	DC current per I/O pin	300 μ A
I _{IOPIN} (AC)	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX} (DC)	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX} (DC)	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C \, dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 4 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Differential on-chip termination resistors ⁽²¹⁾	85- Ω setting	—	85 \pm 30%	—	—	85 \pm 30%	—	—	85 \pm 30%	—	Ω
	100- Ω setting	—	100 \pm 30%	—	—	100 \pm 30%	—	—	100 \pm 30%	—	Ω
	120- Ω setting	—	120 \pm 30%	—	—	120 \pm 30%	—	—	120 \pm 30%	—	Ω
	150- Ω setting	—	150 \pm 30%	—	—	150 \pm 30%	—	—	150 \pm 30%	—	Ω
V_{ICM} (AC and DC coupled)	$V_{CCR_GXB} = 0.85\text{ V}$ or 0.9 V full bandwidth	—	600	—	—	600	—	—	600	—	mV
	$V_{CCR_GXB} = 0.85\text{ V}$ or 0.9 V half bandwidth	—	600	—	—	600	—	—	600	—	mV
	$V_{CCR_GXB} = 1.0\text{ V}/1.05\text{ V}$ full bandwidth	—	700	—	—	700	—	—	700	—	mV
	$V_{CCR_GXB} = 1.0\text{ V}$ half bandwidth	—	750	—	—	750	—	—	750	—	mV
t_{LTR} ⁽¹¹⁾	—	—	—	10	—	—	10	—	—	10	μs
t_{LTD} ⁽¹²⁾	—	4	—	—	4	—	—	4	—	—	μs
t_{LTD_manual} ⁽¹³⁾	—	4	—	—	4	—	—	4	—	—	μs
$t_{LTR_LTD_manual}$ ⁽¹⁴⁾	—	15	—	—	15	—	—	15	—	—	μs
Run Length	—	—	—	200	—	—	200	—	—	200	UI
Programmable equalization (AC Gain) ⁽¹⁰⁾	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	—	—	16	—	—	16	—	—	16	dB

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 5 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	—	0	—	dB
	DC Gain Setting = 1	—	2	—	—	2	—	—	2	—	dB
	DC Gain Setting = 2	—	4	—	—	4	—	—	4	—	dB
	DC Gain Setting = 3	—	6	—	—	6	—	—	6	—	dB
	DC Gain Setting = 4	—	8	—	—	8	—	—	8	—	dB
Transmitter											
Supported I/O Standards	—	1.4-V and 1.5-V PCML									
Data rate (Standard PCS)	—	600	—	12200	600	—	12200	600	—	8500/ 10312.5 ⁽²⁴⁾	Mbps
Data rate (10G PCS)	—	600	—	14100	600	—	12500	600	—	8500/ 10312.5 ⁽²⁴⁾	Mbps
Differential on- chip termination resistors	85- Ω setting	—	85 \pm 20%	—	—	85 \pm 20%	—	—	85 \pm 20%	—	Ω
	100- Ω setting	—	100 \pm 20%	—	—	100 \pm 20%	—	—	100 \pm 20%	—	Ω
	120- Ω setting	—	120 \pm 20%	—	—	120 \pm 20%	—	—	120 \pm 20%	—	Ω
	150- Ω setting	—	150 \pm 20%	—	—	150 \pm 20%	—	—	150 \pm 20%	—	Ω
V _{OCM} (AC coupled)	0.65-V setting	—	650	—	—	650	—	—	650	—	mV
V _{OCM} (DC coupled)	—	—	650	—	—	650	—	—	650	—	mV
Rise time ⁽⁷⁾	20% to 80%	30	—	160	30	—	160	30	—	160	ps
Fall time ⁽⁷⁾	80% to 20%	30	—	160	30	—	160	30	—	160	ps
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps	—	—	15	—	—	15	—	—	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	—	—	120	—	—	120	—	—	120	ps

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 6 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode	—	—	500	—	—	500	—	—	500	ps
CMU PLL											
Supported Data Range	—	600	—	12500	600	—	12500	600	—	8500/ 10312.5 ⁽²⁴⁾	Mbps
t _{pll_powerdown} ⁽¹⁵⁾	—	1	—	—	1	—	—	1	—	—	μs
t _{pll_lock} ⁽¹⁶⁾	—	—	—	10	—	—	10	—	—	10	μs
ATX PLL											
Supported Data Rate Range	VCO post-divider L=2	8000	—	14100	8000	—	12500	8000	—	8500/ 10312.5 ⁽²⁴⁾	Mbps
	L=4	4000	—	7050	4000	—	6600	4000	—	6600	Mbps
	L=8	2000	—	3525	2000	—	3300	2000	—	3300	Mbps
	L=8, Local/Central Clock Divider =2	1000	—	1762.5	1000	—	1762.5	1000	—	1762.5	Mbps
t _{pll_powerdown} ⁽¹⁵⁾	—	1	—	—	1	—	—	1	—	—	μs
t _{pll_lock} ⁽¹⁶⁾	—	—	—	10	—	—	10	—	—	10	μs
fPLL											
Supported Data Range	—	600	—	3250/ 3125 ⁽²⁵⁾	600	—	3250/ 3125 ⁽²⁵⁾	600	—	3250/ 3125 ⁽²⁵⁾	Mbps
t _{pll_powerdown} ⁽¹⁵⁾	—	1	—	—	1	—	—	1	—	—	μs

Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate ⁽¹⁾, ⁽³⁾

Mode ⁽²⁾	Transceiver Speed Grade	PMA Width	20	20	16	16	10	10	8	8
		PCS/Core Width	40	20	32	16	20	10	16	8
FIFO	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
		C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
	3	C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
		I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
		C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
Register	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
		C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
	3	C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
		I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
		C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

Notes to Table 25:

- (1) The maximum data rate is in Gbps.
- (2) The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.
- (3) The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5) ⁽¹⁾

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Transmitter REFCLK Phase Noise (622 MHz) ⁽¹⁸⁾	100 Hz	—	—	-70	—	—	-70	dBc/Hz
	1 kHz	—	—	-90	—	—	-90	
	10 kHz	—	—	-100	—	—	-100	
	100 kHz	—	—	-110	—	—	-110	
	≥ 1 MHz	—	—	-120	—	—	-120	
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCIe)	—	—	3	—	—	3	ps (rms)
RREF ⁽¹⁷⁾	—	—	1800 ± 1%	—	—	1800 ± 1%	—	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect	—	100 or 125	—	—	100 or 125	—	MHz
Reconfiguration clock (mgmt_clk_clk) frequency	—	100	—	125	100	—	125	MHz
Receiver								
Supported I/O Standards	—	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS						
Data rate (Standard PCS) ⁽²¹⁾	GX channels	600	—	8500	600	—	8500	Mbps
Data rate (10G PCS) ⁽²¹⁾	GX channels	600	—	12,500	600	—	12,500	Mbps
Data rate	GT channels	19,600	—	28,050	19,600	—	25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	—	—	1.2	—	—	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	—	—	-0.4	—	—	V
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GT channels	—	—	1.6	—	—	1.6	V
	GX channels	⁽⁸⁾						
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after device configuration ⁽¹⁶⁾ , ⁽²⁰⁾	GT channels V _{CCR_GTB} = 1.05 V (V _{ICM} = 0.65 V)	—	—	2.2	—	—	2.2	V
	GX channels	⁽⁸⁾						
Minimum differential eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GT channels	200	—	—	200	—	—	mV
	GX channels	⁽⁸⁾						

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5) ⁽¹⁾

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Differential on-chip termination resistors ⁽⁷⁾	GT channels	—	100	—	—	100	—	Ω
Differential on-chip termination resistors for GX channels ⁽¹⁹⁾	85- Ω setting	—	85 \pm 30%	—	—	85 \pm 30%	—	Ω
	100- Ω setting	—	100 \pm 30%	—	—	100 \pm 30%	—	Ω
	120- Ω setting	—	120 \pm 30%	—	—	120 \pm 30%	—	Ω
	150- Ω setting	—	150 \pm 30%	—	—	150 \pm 30%	—	Ω
V _{ICM} (AC coupled)	GT channels	—	650	—	—	650	—	mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 0.85 V or 0.9 V	—	600	—	—	600	—	mV
	VCCR_GXB = 1.0 V full bandwidth	—	700	—	—	700	—	mV
	VCCR_GXB = 1.0 V half bandwidth	—	750	—	—	750	—	mV
t _{LTR} ⁽⁹⁾	—	—	—	10	—	—	10	μ s
t _{LTD} ⁽¹⁰⁾	—	4	—	—	4	—	—	μ s
t _{LTD_manual} ⁽¹¹⁾	—	4	—	—	4	—	—	μ s
t _{LTR_LTD_manual} ⁽¹²⁾	—	15	—	—	15	—	—	μ s
Run Length	GT channels	—	—	72	—	—	72	CID
	GX channels	⁽⁸⁾						
CDR PPM	GT channels	—	—	1000	—	—	1000	\pm PPM
	GX channels	⁽⁸⁾						
Programmable equalization (AC Gain) ⁽⁵⁾	GT channels	—	—	14	—	—	14	dB
	GX channels	⁽⁸⁾						
Programmable DC gain ⁽⁶⁾	GT channels	—	—	7.5	—	—	7.5	dB
	GX channels	⁽⁸⁾						
Differential on-chip termination resistors ⁽⁷⁾	GT channels	—	100	—	—	100	—	Ω
Transmitter								
Supported I/O Standards	—	1.4-V and 1.5-V PCML						
Data rate (Standard PCS)	GX channels	600	—	8500	600	—	8500	Mbps
Data rate (10G PCS)	GX channels	600	—	12,500	600	—	12,500	Mbps

Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Symbol	Parameter	Min	Typ	Max	Unit
t_{INCCJ} ^{(3), (4)}	Input clock cycle-to-cycle jitter ($f_{\text{REF}} \geq 100$ MHz)	—	—	0.15	UI (p-p)
	Input clock cycle-to-cycle jitter ($f_{\text{REF}} < 100$ MHz)	−750	—	+750	ps (p-p)
$t_{\text{OUTPJ_DC}}$ ⁽⁵⁾	Period Jitter for dedicated clock output ($f_{\text{OUT}} \geq 100$ MHz)	—	—	175 ⁽¹⁾	ps (p-p)
	Period Jitter for dedicated clock output ($f_{\text{OUT}} < 100$ MHz)	—	—	17.5 ⁽¹⁾	mUI (p-p)
$t_{\text{FOUTPJ_DC}}$ ⁽⁵⁾	Period Jitter for dedicated clock output in fractional PLL ($f_{\text{OUT}} \geq 100$ MHz)	—	—	250 ⁽¹¹⁾ , 175 ⁽¹²⁾	ps (p-p)
	Period Jitter for dedicated clock output in fractional PLL ($f_{\text{OUT}} < 100$ MHz)	—	—	25 ⁽¹¹⁾ , 17.5 ⁽¹²⁾	mUI (p-p)
$t_{\text{OUTCCJ_DC}}$ ⁽⁵⁾	Cycle-to-Cycle Jitter for a dedicated clock output ($f_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Cycle-to-Cycle Jitter for a dedicated clock output ($f_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$t_{\text{FOUTCCJ_DC}}$ ⁽⁵⁾	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ($f_{\text{OUT}} \geq 100$ MHz)	—	—	250 ⁽¹¹⁾ , 175 ⁽¹²⁾	ps (p-p)
	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ($f_{\text{OUT}} < 100$ MHz)+	—	—	25 ⁽¹¹⁾ , 17.5 ⁽¹²⁾	mUI (p-p)
$t_{\text{OUTPJ_IO}}$ ^{(5), (8)}	Period Jitter for a clock output on a regular I/O in integer PLL ($f_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for a clock output on a regular I/O ($f_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{FOUTPJ_IO}}$ ^{(5), (8), (11)}	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{\text{OUT}} \geq 100$ MHz)	—	—	600 ⁽¹⁰⁾	ps (p-p)
	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{\text{OUT}} < 100$ MHz)	—	—	60 ⁽¹⁰⁾	mUI (p-p)
$t_{\text{OUTCCJ_IO}}$ ^{(5), (8)}	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ($f_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ($f_{\text{OUT}} < 100$ MHz)	—	—	60 ⁽¹⁰⁾	mUI (p-p)
$t_{\text{FOUTCCJ_IO}}$ ^{(5), (8), (11)}	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{\text{OUT}} \geq 100$ MHz)	—	—	600 ⁽¹⁰⁾	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{CASC_OUTPJ_DC}}$ ^{(5), (6)}	Period Jitter for a dedicated clock output in cascaded PLLs ($f_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Period Jitter for a dedicated clock output in cascaded PLLs ($f_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
f_{DRIFT}	Frequency drift after PFDENA is disabled for a duration of 100 μ s	—	—	± 10	%
dK_{BIT}	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k_{VALUE}	Numerator of Fraction	128	8388608	2147483648	—

Table 36. High-Speed I/O Specifications for Stratix V Devices ^{(1), (2)} (Part 2 of 4)

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4,I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Transmitter														
True Differential I/O Standards - f _{HSDR} (data rate)	SERDES factor J = 3 to 10 ^{(9), (11), (12), (13), (14), (15), (16)}	(6)	—	1600	(6)	—	1434	(6)	—	1250	(6)	—	1050	Mbps
	SERDES factor J ≥ 4 LVDS TX with DPA ^{(12), (14), (15), (16)}	(6)	—	1600	(6)	—	1600	(6)	—	1600	(6)	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f _{HSDR} (data rate) ⁽¹⁰⁾	SERDES factor J = 4 to 10 ⁽¹⁷⁾	(6)	—	1100	(6)	—	1100	(6)	—	840	(6)	—	840	Mbps
t _{x Jitter} - True Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	—	—	160	—	—	160	—	—	160	—	—	160	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.1	—	—	0.1	—	—	0.1	—	—	0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards with Three External Output Resistor Network	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	—	—	300	—	—	300	—	—	300	—	—	325	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.2	—	—	0.2	—	—	0.2	—	—	0.25	UI

Table 36. High-Speed I/O Specifications for Stratix V Devices ⁽¹⁾, ⁽²⁾ (Part 3 of 4)

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t_{DUTY}	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
t_{RISE} & t_{FALL}	True Differential I/O Standards	—	—	160	—	—	160	—	—	200	—	—	200	ps
	Emulated Differential I/O Standards with three external output resistor networks	—	—	250	—	—	250	—	—	250	—	—	300	ps
TCCS	True Differential I/O Standards	—	—	150	—	—	150	—	—	150	—	—	150	ps
	Emulated Differential I/O Standards	—	—	300	—	—	300	—	—	300	—	—	300	ps
Receiver														
True Differential I/O Standards - f_{HSDRDP} (data rate)	SERDES factor J = 3 to 10 ⁽¹¹⁾ , ⁽¹²⁾ , ⁽¹³⁾ , ⁽¹⁴⁾ , ⁽¹⁵⁾ , ⁽¹⁶⁾	150	—	1434	150	—	1434	150	—	1250	150	—	1050	Mbps
	SERDES factor J ≥ 4	150	—	1600	150	—	1600	150	—	1600	150	—	1250	Mbps
	LVDS RX with DPA ⁽¹²⁾ , ⁽¹⁴⁾ , ⁽¹⁵⁾ , ⁽¹⁶⁾	150	—	1600	150	—	1600	150	—	1600	150	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	⁽⁶⁾	—	⁽⁷⁾	⁽⁶⁾	—	⁽⁷⁾	⁽⁶⁾	—	⁽⁷⁾	⁽⁶⁾	—	⁽⁷⁾	Mbps
	SERDES factor J = 1, uses SDR Register	⁽⁶⁾	—	⁽⁷⁾	⁽⁶⁾	—	⁽⁷⁾	⁽⁶⁾	—	⁽⁷⁾	⁽⁶⁾	—	⁽⁷⁾	Mbps

Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled



Table 37 lists the DPA lock time specifications for Stratix V devices.

Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only ^{(1), (2), (3)}

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions ⁽⁴⁾	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

Notes to Table 37:

- (1) The DPA lock time is for one channel.
- (2) One data transition is defined as a 0-to-1 or 1-to-0 transition.
- (3) The DPA lock time stated in this table applies to both commercial and industrial grade.
- (4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the LVDS soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate ≥ 1.25 Gbps. Table 38 lists the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate ≥ 1.25 Gbps.

Figure 8. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate ≥ 1.25 Gbps



Duty Cycle Distortion (DCD) Specifications

Table 44 lists the worst-case DCD for Stratix V devices.

Table 44. Worst-Case DCD on Stratix V I/O Pins ⁽¹⁾

Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4, I4		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

Note to Table 44:

(1) The DCD numbers do not cover the core clock network.

Configuration Specification

POR Delay Specification

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.



For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

Table 45. Fast and Standard POR Delay Specification ⁽¹⁾

POR Delay	Minimum	Maximum
Fast	4 ms	12 ms
Standard	100 ms	300 ms

Note to Table 45:

(1) You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

JTAG Configuration Specifications

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Symbol	Description	Min	Max	Unit
t _{JCP}	TCK clock period ⁽²⁾	30	—	ns
t _{JCP}	TCK clock period ⁽²⁾	167	—	ns
t _{JCH}	TCK clock high time ⁽²⁾	14	—	ns
t _{JCL}	TCK clock low time ⁽²⁾	14	—	ns
t _{JPSU (TDI)}	TDI JTAG port setup time	2	—	ns
t _{JPSU (TMS)}	TMS JTAG port setup time	3	—	ns

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) ^{(4), (5)}
Stratix V E ⁽¹⁾	5SEE9	—	342,742,976	700,888
	5SEEB	—	342,742,976	700,888

Notes to Table 47:

- (1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.tff) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.



For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices*. For creating configuration files, refer to the *Quartus II Help*.

Table 48 lists the minimum configuration time estimates for Stratix V devices.

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Variant	Member Code	Active Serial ⁽¹⁾			Fast Passive Parallel ⁽²⁾		
		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
GX	A3	4	100	0.534	32	100	0.067
		4	100	0.344	32	100	0.043
	A4	4	100	0.534	32	100	0.067
	A5	4	100	0.675	32	100	0.084
	A7	4	100	0.675	32	100	0.084
	A9	4	100	0.857	32	100	0.107
	AB	4	100	0.857	32	100	0.107
	B5	4	100	0.676	32	100	0.085
	B6	4	100	0.676	32	100	0.085
	B9	4	100	0.857	32	100	0.107
	BB	4	100	0.857	32	100	0.107
GT	C5	4	100	0.675	32	100	0.084
	C7	4	100	0.675	32	100	0.084

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Variant	Member Code	Active Serial ⁽¹⁾			Fast Passive Parallel ⁽²⁾		
		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
GS	D3	4	100	0.344	32	100	0.043
	D4	4	100	0.534	32	100	0.067
		4	100	0.344	32	100	0.043
	D5	4	100	0.534	32	100	0.067
	D6	4	100	0.741	32	100	0.093
	D8	4	100	0.741	32	100	0.093
E	E9	4	100	0.857	32	100	0.107
	EB	4	100	0.857	32	100	0.107

Notes to Table 48:

- (1) DCLK frequency of 100 MHz using external CLKUSR.
 (2) Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Fast Passive Parallel Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA [] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA [] ratio for each combination.

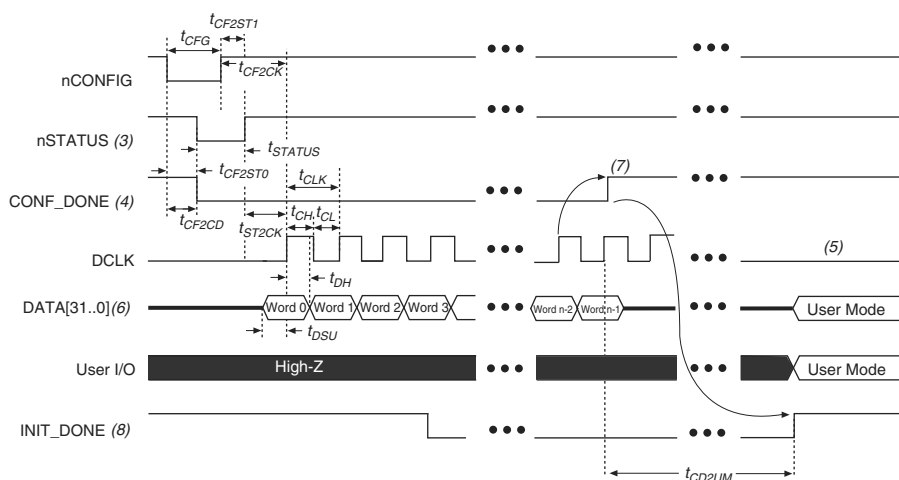
Table 49. DCLK-to-DATA[] Ratio ⁽¹⁾ (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×8	Disabled	Disabled	1
	Disabled	Enabled	1
	Enabled	Disabled	2
	Enabled	Enabled	2
FPP ×16	Disabled	Disabled	1
	Disabled	Enabled	2
	Enabled	Disabled	4
	Enabled	Enabled	4

FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is 1.

Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 ^{(1), (2)}



Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA [] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF_DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP $\times 16$, use DATA [15..0]. For FPP $\times 8$, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions
S	SW (sampling window)	<p>Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:</p>
	Single-ended voltage referenced I/O standard	<p>The JEDEC standard for SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.</p> <p>The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing:</p> <p><i>Single-Ended Voltage Referenced I/O Standard</i></p>
T	t_c	High-speed receiver and transmitter input and output clock period.
	TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under SW in this table).
	t_{DUTY}	<p>High-speed I/O block—Duty cycle on the high-speed transmitter output clock.</p> <p>Timing Unit Interval (TUI)</p> <p>The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_c/w$)</p>
	t_{FALL}	Signal high-to-low transition time (80-20%)
	t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.
	t_{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.
	t_{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.
	t_{RISE}	Signal low-to-high transition time (20-80%)
U	—	—

Table 60. Glossary (Part 4 of 4)

Letter	Subject	Definitions
V	$V_{CM(DC)}$	DC common mode input voltage.
	V_{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
	V_{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
	V_{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage
	$V_{IH(DC)}$	High-level DC input voltage
	V_{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage
	$V_{IL(DC)}$	Low-level DC input voltage
	V_{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
	V_{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	V_{SWING}	Differential input voltage
	V_X	Input differential cross point voltage
	V_{OX}	Output differential cross point voltage
W	W	High-speed I/O block—clock boost factor
X	—	—
Y		
Z		